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ABSTRACT

The present invention provides a heat-resistant resin film with a metal layer strongly bonded to the heat-resistant resin film without deteriorating the physical properties possessed by the heat-resistant resin film, and a wiring board using the heat-resistant resin film with the metal layer.

The heat-resistant resin film with the metal layer includes a heat-resistant adhesive coated on at least one side of the heat-resistant resin film, and the metal layer provided on the heat-resistant adhesive by at least one of sputtering, vacuum evaporation, and plating. The heat-resistant adhesive has a glass transition temperature (Tg) of 60°C to 250°C, generates 250 ppm or less of gases at 100°C to 300°C, and has an elastic modulus of 0.1 GPa to 3 GPa at 200°C. The wiring board uses the heat-resistant resin film with the metal layer.